

Amendments to the Claims

1 - 14 (Canceled)

15. (New) A coaxial via structure in an electronic device carrier adapted to connect power/ground voltage comprising:

- a first conductive track of a first conductive layer on a first surface of a dielectric core to a second conductive track on a second conductive layer in a central portion of said dielectric core, and a third conductive track of a third conductive layer, said conductive layers being separated by dielectric layers;
- a coaxial via structure having at least two first conductive vias for conducting voltage only connected to said first and second conductive tracks;
- at least two second conductive vias for conducting voltage only connected to said second and third conductive tracks;
- a fourth conductive track of a fourth conductive layer surrounding said first conductive layer;
- a fifth conductive track of a fifth conductive layer surrounding said second conductive layer;
- a sixth conductive track of a sixth conductive layer surrounding said third conductive layer;
- at least two third conductive vias for conducting voltage only connected to said fourth and fifth conductive tracks; and

at least two fourth conductive vias conducting voltage only connected to said fifth and sixth conductive tracks.

16. (New) The structure as defined in claim 15 wherein there are at least four vias of either the first set of vias or the second set of vias.

17. (New) The structure as defined in claim 15 wherein the vias of at least one set of vias are symmetrically arranged with respect to each other.

18. (New) The structure as defined in claim 15 wherein the vias of each set of vias are symmetrically arranged with respect to each other.

19. (New) The structure as defined in claim 17 wherein the vias of each set are symmetrically arranged with respect to each other.